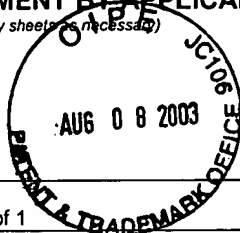


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STATEMENT BY APPLICANT**
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First Named Inventor Ahn, Kie
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Examiner Name Duda, Kathleen

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Sheet 1 of 1

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US PATENT DOCUMENTS

Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	Filing Date If Appropriate
KMD	US-5,384,284	01/24/1995	Doan, T T., et al.	437	190	10/01/1993
KMD	US-5,495,667	03/05/1996	Farnworth, Warren M., et al.	29	843	11/07/1994
KMD	US-5,925,930	07/20/1999	Farnworth, Warren M., et al.	257	737	05/21/1996
KMD	US-6,037,248	03/14/2000	Ahn, Kie	438	619	06/13/1997
KMD	US-6,126,989	10/03/2000	Robinson, Karl, et al.	427	97	08/26/1998
KMD	US-6,159,769	12/12/2000	Farnworth, Warren M., et al.	438	108	01/05/1999
KMD	US-6,211,049	04/03/2001	Farrar, Paul A.	438	597	02/24/1999
KMD	US-6,221,763	04/24/2001	Gilton, Terry L.	438	643	04/05/1999
KMD	US-6,326,303	12/04/2001	Robinson, Karl, et al.	438	678	02/11/2000
KMD	US-6,518,198	02/11/2003	Klein, Rita J.	438	758	08/31/2000

FOREIGN PATENT DOCUMENTS

Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	T ²
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OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
KMD		BAI, G., "Copper Interconnection Deposition Techniques and Integration", 1996 Symposium on VLSI Technology, Digest of Technical Papers, (1996), 48-49	

EXAMINER

K. Duda

DATE CONSIDERED

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